In the Specification

At p. 1 before the "Technical Field" section, please insert the following:

-RELATED PATENT DATA

This patent resulted from a divisional application of U.S. Patent Application Serial No. 09/022,812, filed February 12, 1998, entitled "Thin Profile Battery Bonding Method and Method of Conductively Interconnecting Electronic Components" (As Amended), naming Rickie C. Lake as inventor, and which is now U.S. Patent No. 6,030423, the disclosure of which is incorporated by reference.--

Delete the language starting on Page 9, line 20, starting with the word "Example" through Page 10, line 12 through "disclosures.", as directed to non-essential matter.

In the Claims

Cancel claims 1-8 and 15-22 without prejudice.

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